

**CLUSTER TOOL SYSTEMS AND METHODS
FOR PROCESSING WAFERS**

ABSTRACT OF THE DISCLOSURE

The present invention provides exemplary cluster tool systems and methods
5 for processing wafers, such as semiconductor wafers. One method includes providing a
wafer having initial thickness variations between two wafer surfaces. The wafer is processed
(Step 216) through a first module (300), with the first module having apparatus for
performing a grinding process, a clean process and a metrology process, all preferably within
a clean room environment (310). Wafer processing through the first module includes
10 performing the grinding process, clean process and metrology process. The method further
includes defining an edge profile on the wafer and processing (Step 222) the wafer through a
second module (400).

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